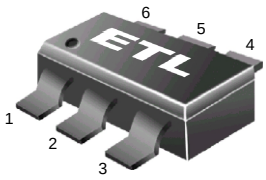
ETL SEMICONDUCTOR

# Low Voltage Bias Stabilizer with Enable

**MDC5001T1**

**SILICON SMALLBLOCK™ INTEGRATED CIRCUIT**




**SOT–363**
**CASE 419B–01 STYLE 19**

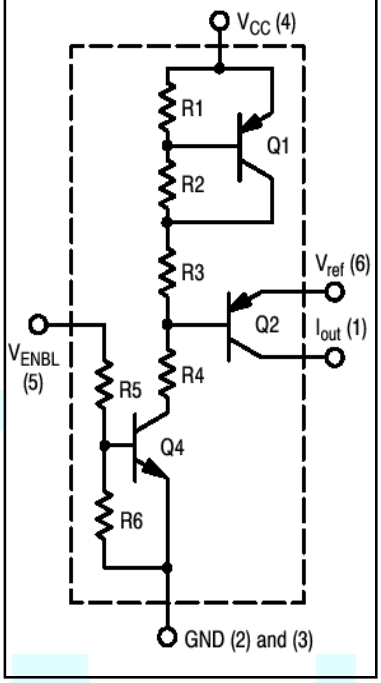
- Maintains Stable Bias Current in N–Type Discrete Bipolar Junction and Field Effect Transistors
- Provides Stable Bias Using a Single Component Without Use of Emitter Ballast and Bypass Components
- Operates Over a Wide Range of Supply Voltages Down to 1.8 Vdc
- Reduces Bias Current Variation Due to Temperature and Unit–to–Unit Parametric Changes
- Consumes <0.5 mW at $V_{CC}$ = 2.75 V
- Active High Enable is CMOS Compatible

This device provides a reference voltage and acts as a DC feedback element around an external discrete, NPN BJT or N–Channel FET. It allows the external transistor to have its emitter/source directly grounded and still operate with a stable collector/drain DC current. It is primarily intended to stabilize the bias of discrete RF stages operating from a low voltage regulated supply, but can also be used to stabilize the bias current of any linear stage in order to eliminate emitter/source bypassing and achieve tighter bias regulation over temperature and unit variations. The “ENABLE” polarity nulls internal current, Enable current, and RF transistor current in “STANDBY.” This device is intended to replace a circuit of three to six discrete components.

The combination of low supply voltage, low quiescent current drain, and small package make the MDC5001T1 ideal for portable communications applications such as:

- Cellular Telephones
- Pagers
- PCN/PCS Portables
- GPS Receivers
- PCMCIA RF Modems
- Cordless Phones
- Broadband and Multiband Transceivers and Other Portable Wireless Products.

**INTERNAL CIRCUIT DIAGRAM**



**MDC5001T1**

**MAXIMUM RATINGS**

| Rating | Symbol | Value | Unit |
|---|---|---|---|
| Power Supply Voltage | $V_{CC}$ | 15 | $V_{dc}$ |
| Ambient Operating Temperature Range | $T_A$ | –40 to +85 | °C |
| Storage Temperature Range | $T_{stg}$ | –65 to +150 | °C |
| Junction Temperature | $T_J$ | 150 | °C |
| Collector Emitter Voltage (Q2) | $V_{CEO}$ | –15 | V |
| Enable Voltage (Pin 5) | $V_{ENBL}$ | $V_{CC}$ | V |

**THERMAL CHARACTERISTICS**

| Characteristic | Symbol | Max | Unit |
|---|---|---|---|
| Total Device Power Dissipation | P D | | mW |
| (FR–5 PCB of 1, × 0.75, × 0.062,, $T_A$ = 25°C) | | 150 | |
| Derate above 25°C | | 1.2 | mW/°C |
| Thermal Resistance, Junction to Ambient | $R_{\theta JA}$ | 833 | °C/W |

**ELECTRICAL CHARACTERISTICS** ($T_A$ = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| Recommended Operating Supply Voltage | $V_{CC}$ | 1.8 | 2.75 | 10 | Volts |
| Power Supply Current ($V_{CC}$ = 2.75 V) | $I_{CC}$ | — | 130 | 200 | mA |
| $V_{ref}$ , $I_{out}$ are unterminated | | | | | |
| See Figure 8 | | | | | |
| Q2 Collector Emitter Breakdown Voltage | $V_{(BR)CEO2}$ | 15 | | | Volts |
| ($I_{C2}$ = 10 µA, $I_{B2}$ = 0) | | | | | |
| Reference Voltage ($V_{ENBL}$ = $V_{CC}$ = 2.75 V, $V_{out}$ = 0.7 V) | V ref | | | | Volts |
| ($I_{out}$ = 30 µA) | | 2.050 | 2.075 | 2.100 | |
| ($I_{out}$ = 150 µA) | | 2.110 | 2.135 | 2.160 | |
| See Figure 1 | | | | | |
| Reference Voltage ($V_{ENBL}$ = $V_{CC}$ = 2.75 V, $V_{out}$ = 0.7 V, | | | | | |
| –40°C ≤ $T_A$ ≤+85°C) | | | | | |
| $V_{CC}$ Pulse Width = 10 mS, Duty Cycle = 1% | $\Delta V_{ref}$ | | | | mV |
| ($I_{out}$ = 10 µA) | | | ±5.0 | ±10 | |
| ($I_{out}$ = 30 µA) | | | ±15 | ±30 | |
| ($I_{out}$ = 100 µA) | | | ±25 | ±50 | |
| See Figures 2 and 11 | | | | | |

**MDC5001T1**

The following SPICE models are provided as a convenience to the user and every effort has been ade to insure their accuracy. However, no responsibility for their accuracy is assumed by ON Semiconductor.

| .MODEL Q4 NPN | | .MODEL Q1, Q2 PNP | |
|---|---|---|---|
| BF = 136 | NE = 1.6 | BF = 87 | NK = 0.5 |
| BR = 0.2 | NF = 1.005 | BR = 0.6 | NR = 1.0 |
| CJC = 318.6 f | RB = 140 | CJC = 800E–15 | RB = 720 |
| CJE = 569.2 f | RBM = 70 | CJE = 46E–15 | RBM = 470 |
| CJS = 1.9 p | RC = 180 | EG = 1.215 | RC = 180 |
| EG = 1.215 | RE = 1.6 | FC = 0.5 | RE = 26 |
| FC = 0.5 | TF = 553.6 p | IKF = 3.8E–04 | TF = 15E–9 |
| IKF = 24.41 m | TR = 10 n | IKR = 2.0 | TR = 50E–09 |
| IKR = 0.25 | VAF = 267.6 | IRB = 0.9E–3 | VAF = 54.93 |
| IRB = 0.0004 | VAR = 12 | IS = 1.027E–15 | VAR = 20 |
| IS = 256E–18 | VJC = 0.4172 | ISC = 10E–18 | VAR = 20 |
| ISC = 1 f | VJE = 0.7245 | ISE = 1.8E–15 | VJC = 0.4172 |
| ISE = 500E–18 | VJS = 0.39 | ITF = 2E–3 | VJE = 0.4172 |
| ITF = 0.9018 | VTF = 10 | MJC = 0.2161 | VTF = 10 |
| MJC = 0.2161 | XTB = 1.5 | MJE = 0.2161 | XTB = 1.5 |
| MJE = 0.3373 | XTF = 2.077 | NC = 0.8 | XTF = 2.0 |
| MJS = 0.13 | XTI = 3 | NE = 1.38 | XTI = 3 |
| NC = 1.09 | | NF = 1.015 | |

**RESISTOR VALUES**

$R_1$ = 12 K
$R_2$ = 6 K
$R_3$ = 3.4 K
$R_4$ = 12 K
$R_5$ = 20 K
$R_6$ = 40 K

These models can be retrieved electronically by accessing the ON Semiconductor Web page at http://design–net.sps.mot.com/models and searching the section on SMALLBLOCKE models

## TYPICAL OPEN LOOP CHARACTERISTICS

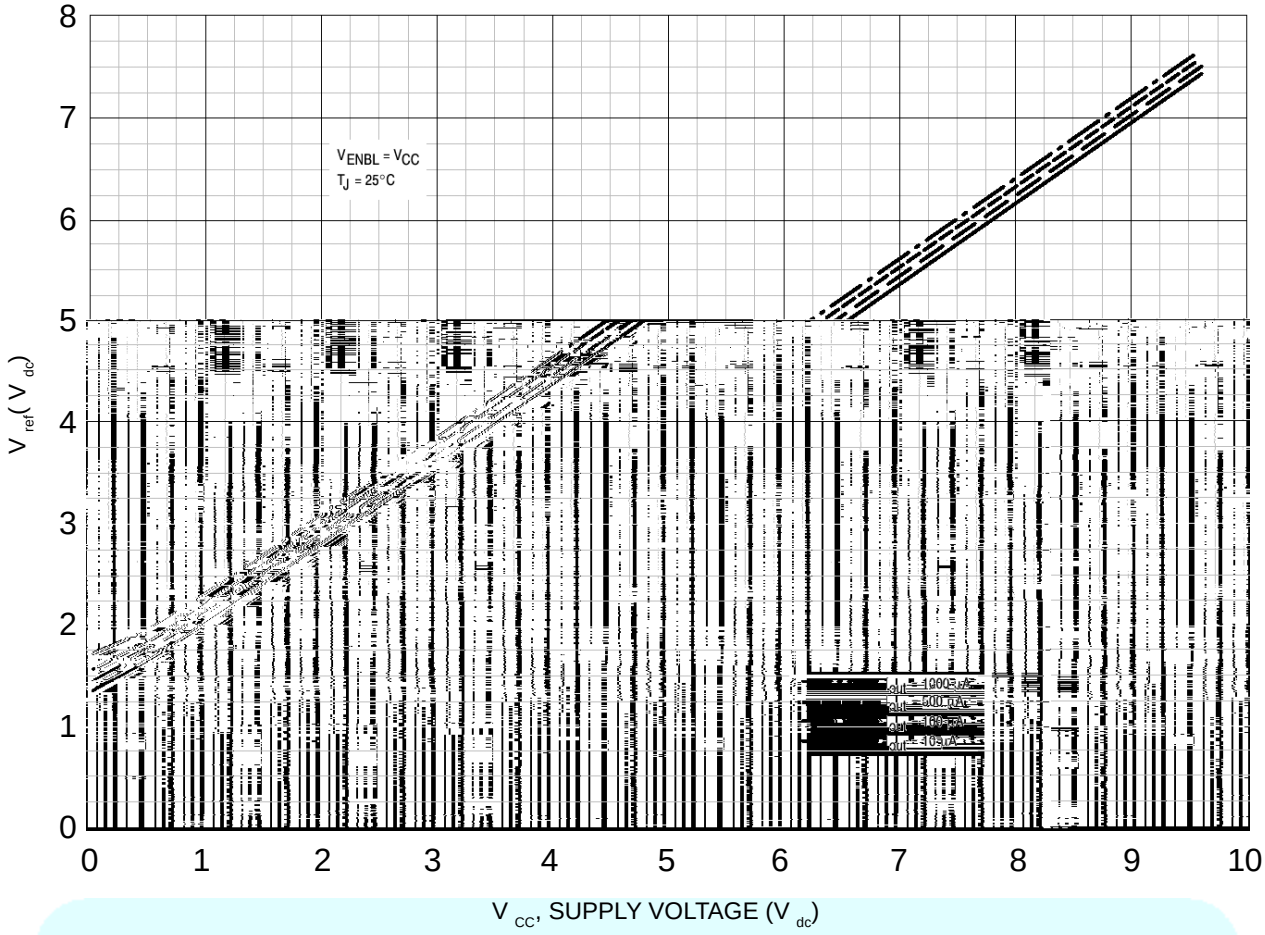



**Figure 1. $V_{ref}$ versus $V_{CC}$ @ $I_{out}$**

## TYPICAL OPEN LOOP CHARACTERISTICS

(Refer to Circuits of Figures 10 through 15)

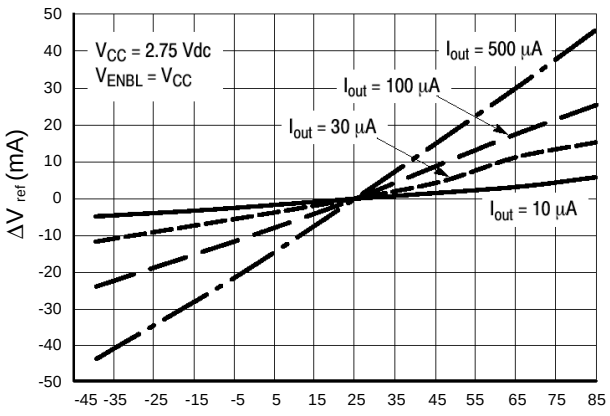



**Figure 2. ΔV ref versus T J @ I out**

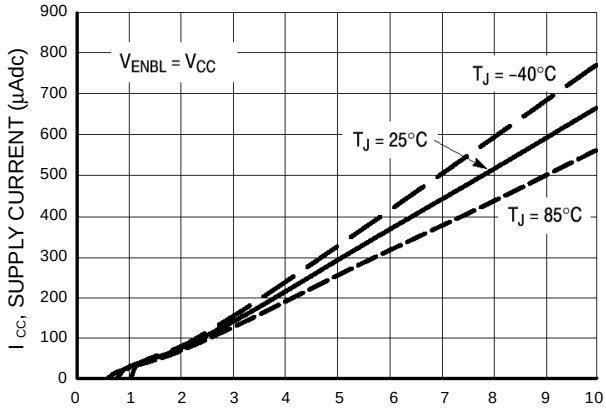



**Figure 3. I CC versus V CC @ T J**

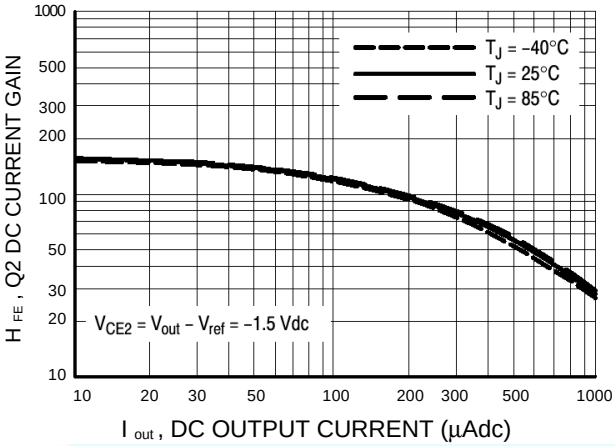



**Figure 4. Q2 Current Gain versus Output Current @ T J**

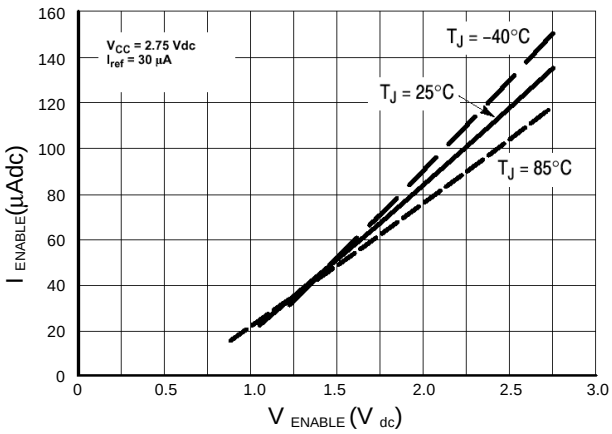



**Figure 5. I enable versus V enable**

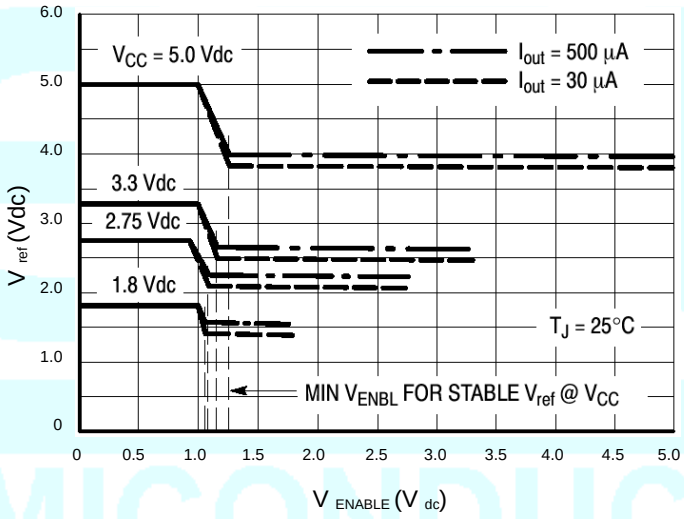



**Figure 6. V ref versus V enable @ V CC and I out**

## TYPICAL CLOSED LOOP PERFORMANCE

(Refer to Circuits of Figures 16 & 17)

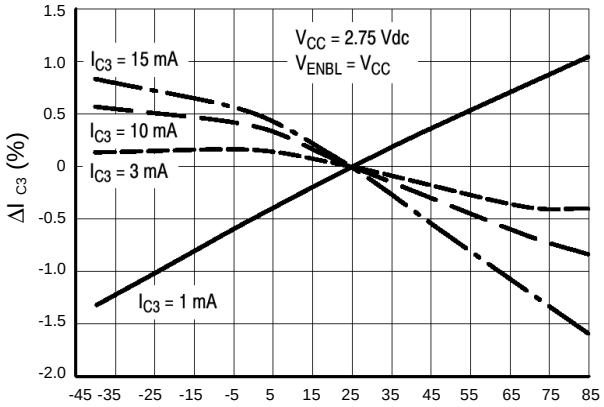



**Figure 7. $\Delta I_{C3}$ versus $T_A$ @ $I_{C3}$**

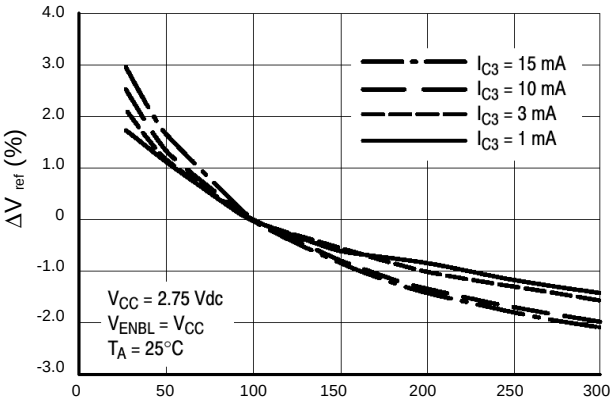



**Figure 8. $\Delta V_{ref}$ versus External Transistor DC Beta @ $I_{C3}$**

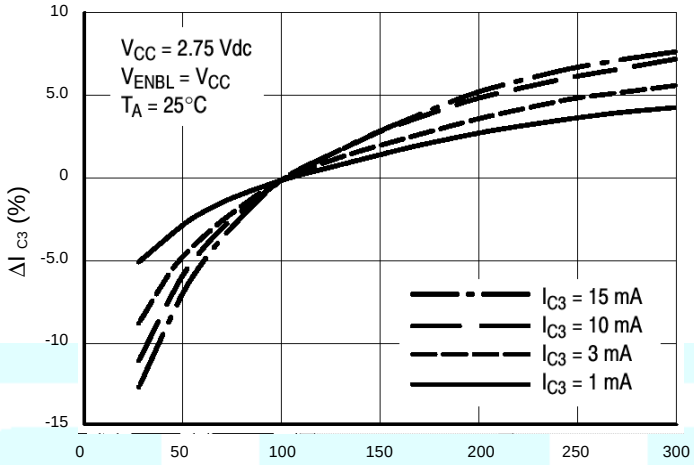



**Figure 9. $\Delta I_{C3}$ versus External Transistor DC Beta @ $I_{C3}$**

## OPEN LOOP TEST CIRCUITS

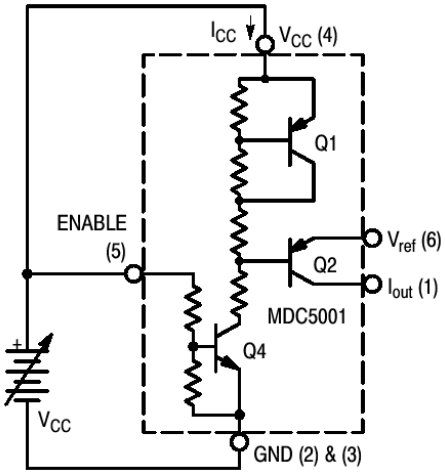



**Figure 10. $I_{CC}$ versus $V_{CC}$ Test Circuit**

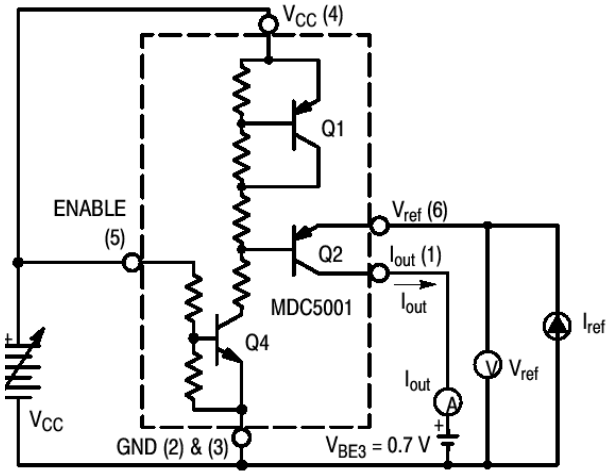



**Figure 11. $V_{ref}$ versus $V_{CC}$ Test Circuit**

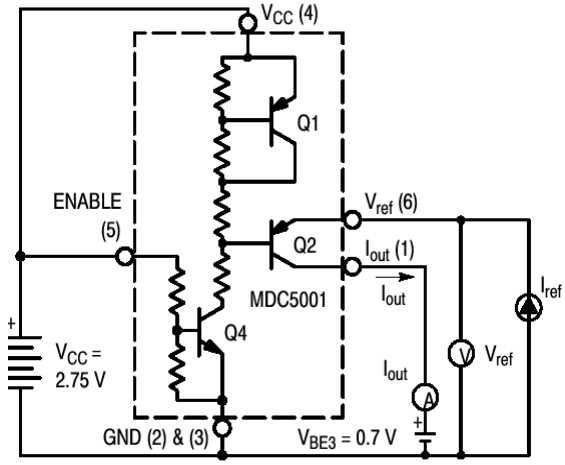



**Figure 12. $V_{ref}$ versus $T_J$ Test Circuit**

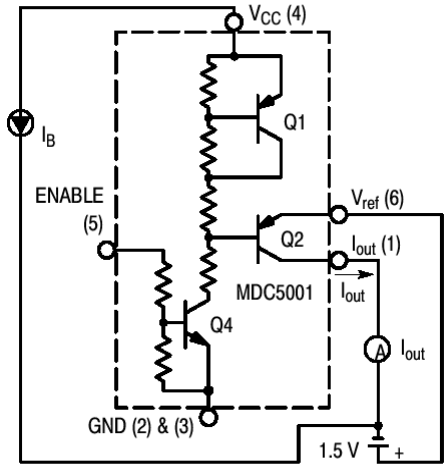



**Figure 13. $H_{FE}$ versus $I_{out}$ Test Circuit**

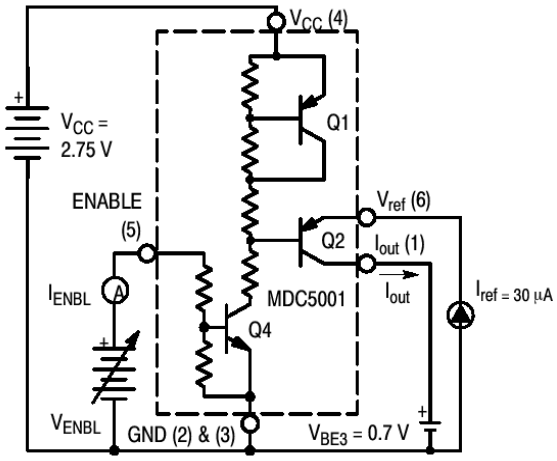



**Figure 14. $I_{ENBL}$ versus $V_{ENBL}$ Test Circuit**

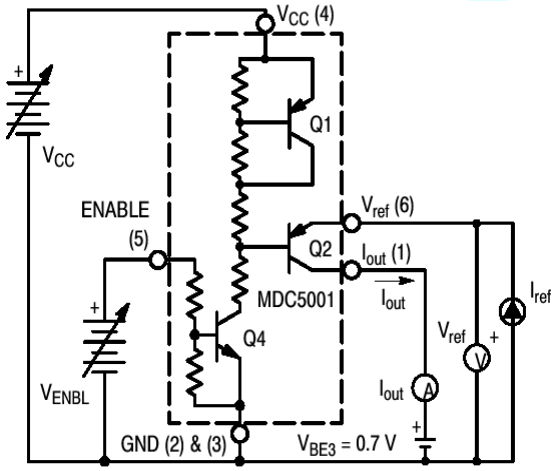



**Figure 15. $V_{ref}$ versus $V_{ENBL}$ Test Circuit**

NOTE 1: $V_{BE3}$ is used to simulate actual operating conditions that reduce $V_{CE2}$ & $H_{FE2}$, and increase $I_{B2}$ & $V_{ref}$.

## CLOSED LOOP TEST CIRCUITS

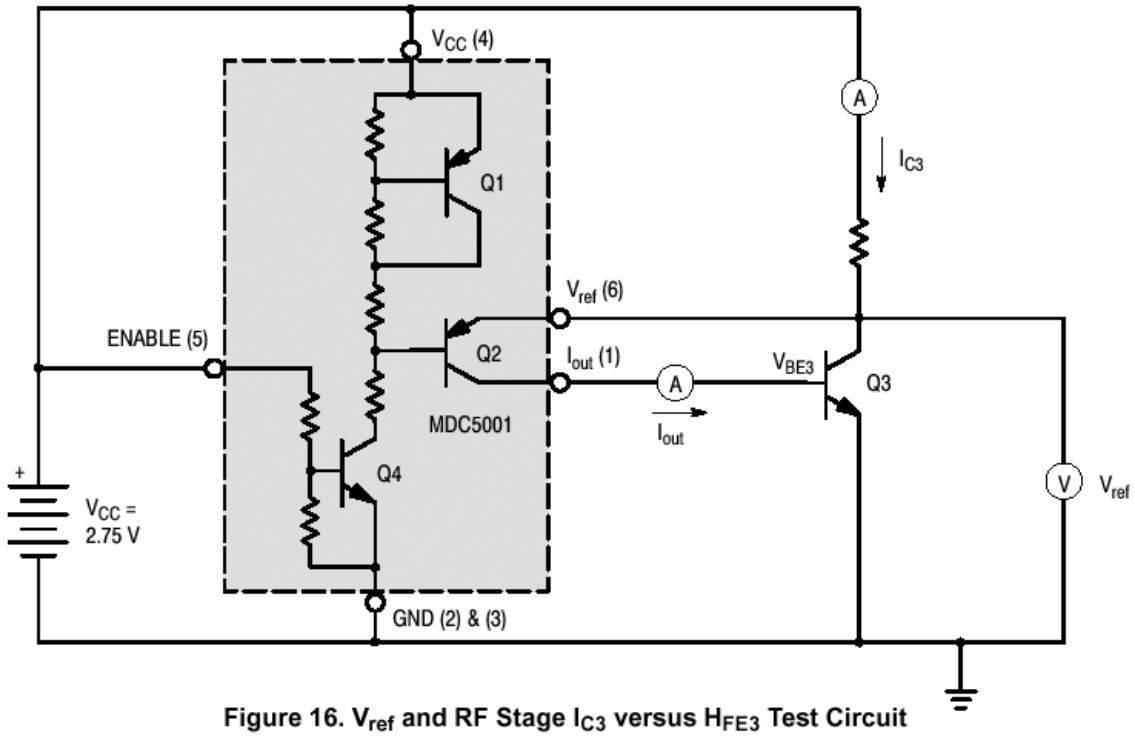



**Figure 16. $V_{ref}$ and RF Stage $I_{C3}$ versus $H_{FE3}$ Test Circuit**

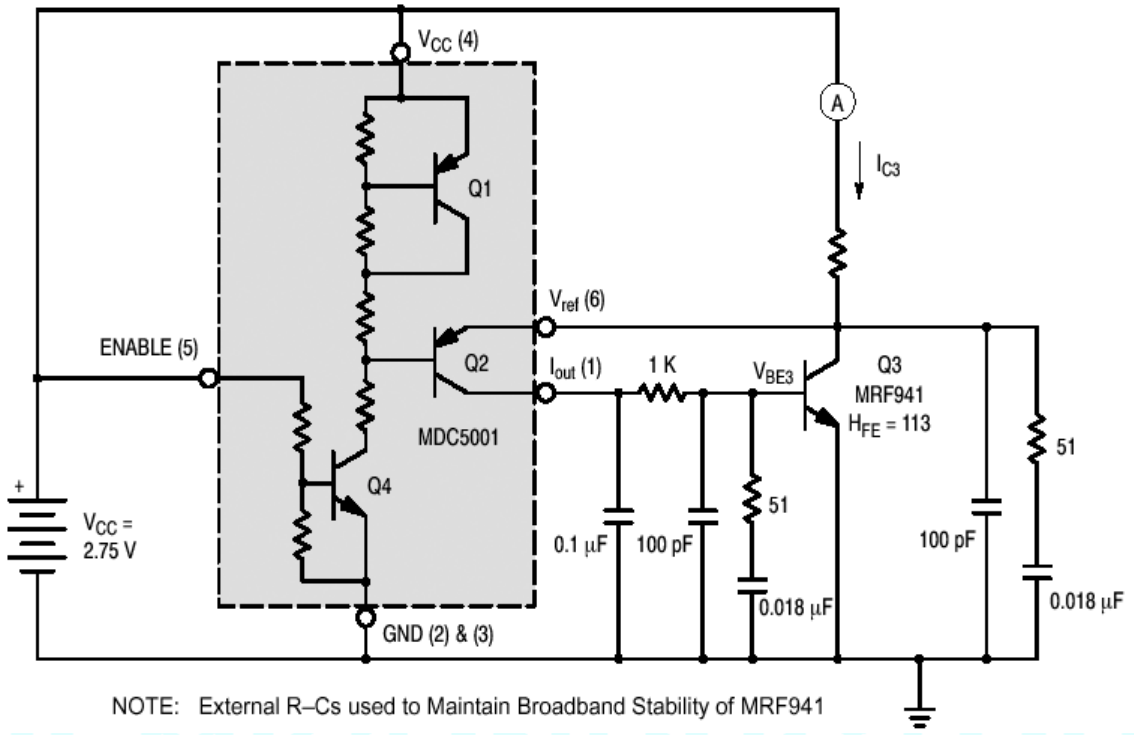
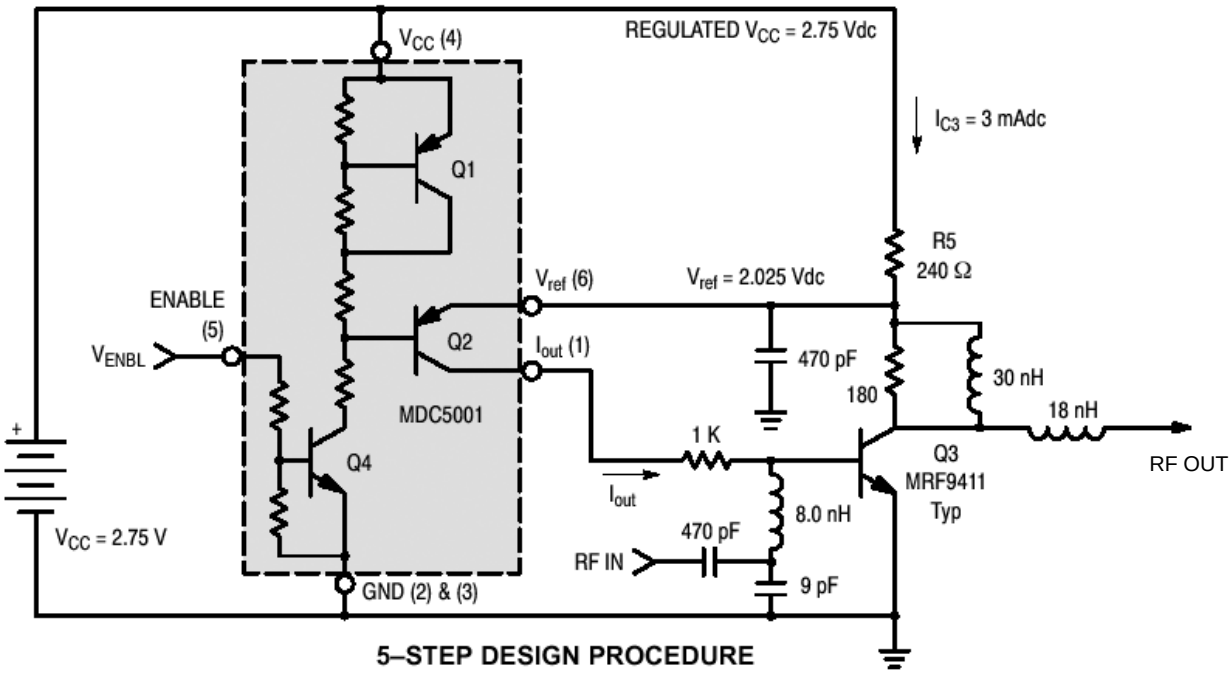



**Figure 17. RF Stage $I_{C3}$ versus $T_A$ Test Circuit**

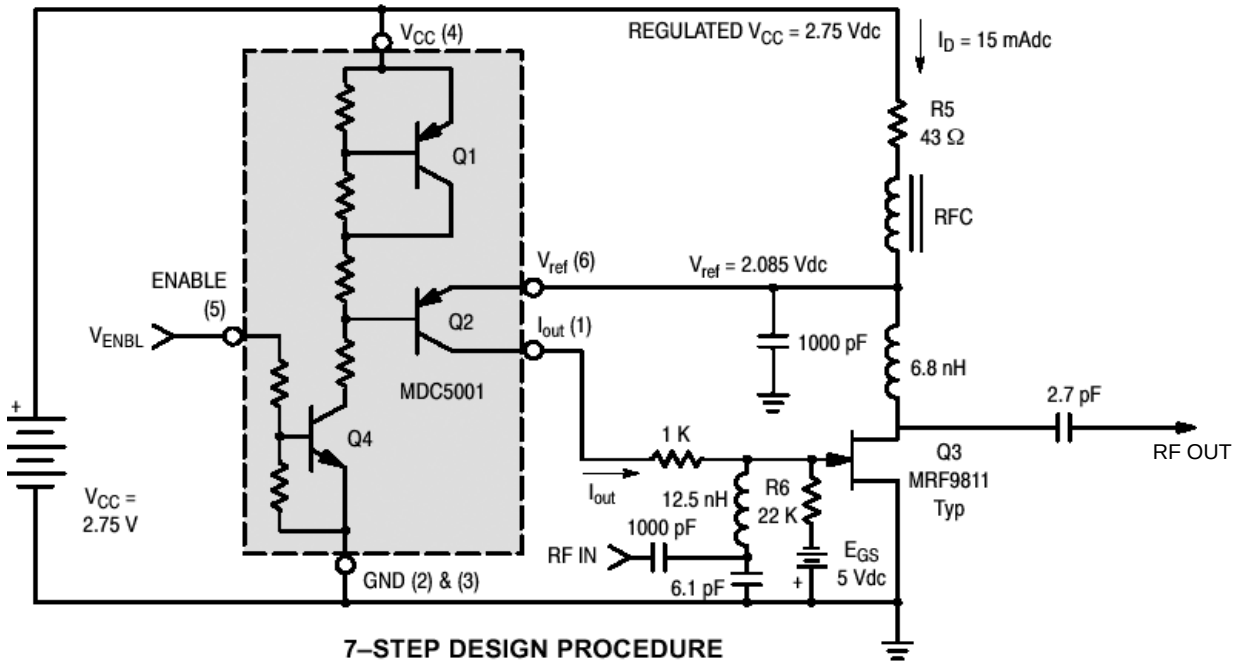
## APPLICATION CIRCUITS




Step 1: Choose $V_{CC}$ (1.8 V Min to 10 V Max)
Step 2: Insure that Min $V_{ENBL}$ is . minimum indicated in Figures 5 and 6.
Step 3: Choose bias current, $I_{C3}$ , and calculate needed $I_{out}$ from typ $H_{FE3}$
Step 4: From Figure 1, read $V_{ref}$ for $V_{CC}$ and $I_{out}$ calculated.
Step 5: Calculate Nominal R5 = ($V_{CC}$ – $V_{ref}$ ) ÷ ($I_{C3}$ + $I_{out}$ ). Tweak as desired.

**Figure 18. Class A Biasing of a Typical 900 MHz BJT Amplifier Application**

## APPLICATION CIRCUITS




### 7–STEP DESIGN PROCEDURE

Step 1: Choose $V_{CC}$ (1.8 V Min to 10 V Max)
Step 2: Insure that Min $V_{ENBL}$ is ≥ minimum indicated in Figures 5 and 6.
Step 3: Choose bias current, $I_D$, and determine needed gate–source voltage, $V_{GS}$.
Step 4: Choose $I_{out}$ keeping in mind that too large an $I_{out}$ can impair MDC5000 $\Delta V_{ref}/\Delta T_J$ performance (Figure 2) but too large an R6 can cause $I_{DGO}$ & $I_{GSO}$ to bias on the FET.
Step 5: Calculate R6 = ($V_{GS}$ + $E_{GS}$) ÷ $I_{out}$
Step 6: From Figure 1, read $V_{ref}$ for $V_{CC}$ & $I_{out}$ chosen
Step 7: Calculate Nominal R5 = ($V_{CC}$ – $V_{ref}$) ÷ ($I_D$ + $I_{out}$). Tweak as desired.

**Figure 19. Class A Biasing of a Typical 890 MHz Depletion Mode GaAs FET Amplifier**